

SOT1462-2

plastic thermal enhanced quad flat package; no leads; 20 terminals; body 8.0 mm x 8.0 mm x 2.1 mm

22 September 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	HQFN
Package type industry code	HQFN20
Package style descriptive code	HQFP
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	13-10-2015

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	7.9	-	8	8.1	mm
E	package width	7.9	-	8	8.1	mm
A	seated height	2	-	2.1	2.2	mm
e	nominal pitch	-	-	1.15	-	mm
n ₂	actual quantity of termination	-	-	20	-	



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2. Package outline

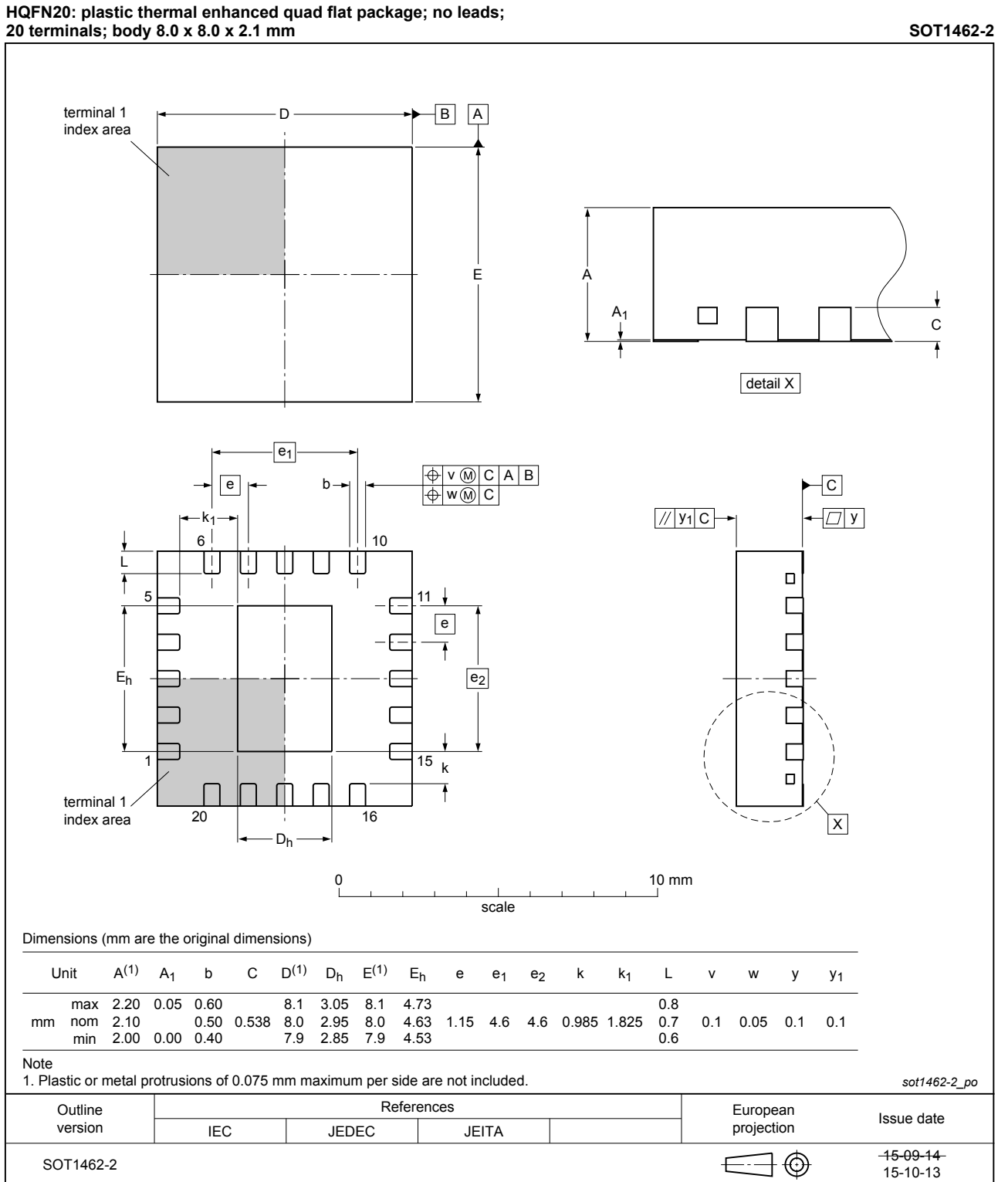


Fig. 1. Package outline HQFN20 (SOT1462-2)

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3. Legal information

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